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(21) International Application Number: PCT/US97/24188 (22) International Filing Date: 29 December 1997 (29.12.97) (30) Priority Data: 08/781,995 6 January 1997 (06.01.97) US (63) Related by Continuation (CON) or Continuation-in-Part (CIP) to Earlier Application US 08/781,995 (CON) Filed on 6 January 1997 (06.01.97) (71) Applicant (for all designated States except US): QUANTUM MATERIALS, INC. [US/US]; 9938 Via Pasar, San Diego, CA 92126 (US). (72) Inventor; and (75) Inventor/Applicant (for US only): FORRAY, Deborah, Derfelt [US/US]; 5190 Biltmore Street, San Diego, CA 92117 (US). (74) Agent: REITER, Stephen, E.; Gray Cary Ware & Freidenrich, Suite 1600, 4365 Executive Drive, San Diego, CA 92121 (US).		(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, GM, GW, HU, ID, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>
(54) Title: REDUCING VOID FORMATION IN CURABLE ADHESIVE FORMULATIONS (57) Abstract In accordance with the present invention, adhesive formulations have been developed which enable curing of adhesively bonded assemblies (i.e., assemblies which comprise devices which have been adhesively bonded to substrates) with dramatically reduced occurrence of void formation upon curing. In many instances, void formation can be eliminated employing invention compositions. In accordance with another aspect of the present invention, methods employing the above-described adhesive formulations are also provided, as are substantially void-free articles produced thereby.		